

(PRIOR ART)

FIG. 1

Component (e.g., a LGA component) 106

Interposer 110

Substrate Electrical Contact Area 108

Substrate (e.g., a printed circuit board) 104

Substrate Electrical Contact Area 102 Interposer 212

Capacitor Plate 214

v1	gnd				v2		
Pad		Pad			Pad		
302		304			340	42.72	
	Dielectric Layer 306		Dielectric I	Layer 306	16		
	Ground Plane 308			ane 308			
	Dielectric Layer 310	Via	Dielectric I	Layer 310	77.7		
	Power Plane 312	336	Power Pl	ane 312		<b>(2)</b>	
Via	Dielectric Layer 314		Dielectric I	Layer 314	Via		
332	Ground Plane 316		Ground P	lane 316	338		
	Dielectric Layer 318		Dielectric I	Layer 318			
	Power Plane 320		Power Pl	ane 320			
	Dielectric Layer 322		Dielectric I	Layer 322			
	Ground Plane 324		Ground P	lane 324			
	Dielectric Layer 326		Dielectric I	Layer 326			
	Power Plane 328		Power Pl	ane 328			
	Dielectric Layer 330		Dielectric I	Layer 330	100		
Pad		Pad		. (6)	Pad	11.11	
342		344			346		

FIG. 3

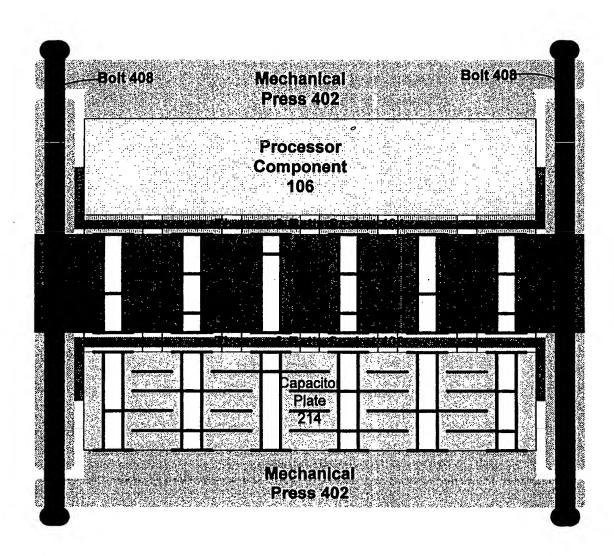


FIG. 4

